

BT136X-600E

Rev.01 - 17 April 2018

**Product data sheet** 

#### **1. General description**

Planar passivated sensitive gate four quadrant triac in a SOT186A (TO-220F) plastic package intended for use in general purpose bidirectional switching and phase control applications. This sensitive gate "series E" triac is intended to be interfaced directly to microcontrollers, logic integrated circuits and other low power gate trigger circuits.

### 2. Features and benefits

- High blocking voltage capability
- Planar passivated for voltage ruggedness and reliability
- Sensitive gate
- Triggering in all four quadrants
- Isolated package
- Direct triggering from low power drivers and logic ICs
- · Low holding current for small load currents and lowest EMI at commutation

#### 3. Applications

- General purpose motor control
- · General purpose switching

### 4. Quick reference data

Symbol	Parameter	Conditions	Values			Unit	
Absolute	e maximum rating	·	I				
V <sub>DRM</sub>	repetitive peak off-state voltage			6	00		V
I <sub>T(RMS)</sub>	RMS on-state current	full sine wave; T <sub>h</sub> ≤92 °C; <u>Fig. 1; Fig. 2; Fig. 3</u>		4		A	
I <sub>TSM</sub>	non-repetitive peak on- state current	full sine wave; T <sub>j(init)</sub> = 25 °C; t <sub>p</sub> = 20 ms; <u>Fig. 4</u> ; <u>Fig. 5</u>		25			A
Symbol	Parameter	Conditions	I	Min	Тур	Max	Unit
Static ch	aracteristics		· · ·				
I <sub>GT</sub>	gate trigger current	V <sub>D</sub> = 12 V; I <sub>T</sub> = 0.1 A; T2+ G+; T <sub>j</sub> = 25 °C; <u>Fig. 7</u>	-		2.5	10	mA
		$V_{D} = 12 \text{ V}; \text{ I}_{T} = 0.1 \text{ A}; \text{ T2+ G-};$ T <sub>j</sub> = 25 °C; Fig. 7	-		4	10	mA
		V <sub>D</sub> = 12 V; I <sub>T</sub> = 0.1 A; T2- G-; T <sub>j</sub> = 25 °C; <u>Fig. 7</u>	-		5	10	mA
		V <sub>D</sub> = 12 V; I <sub>T</sub> = 0.1 A; T2- G+; T <sub>j</sub> = 25 °C; <u>Fig. 7</u>	-		11	25	mA
I <sub>H</sub>	holding current	V <sub>D</sub> = 12 V; T <sub>i</sub> = 25 °C; <u>Fig. 9</u>			2.2	15	mA

# 5. Pinning information

Table 2.	<b>Pinning info</b>	rmation		
Pin	Symbol	Description	Simplified outline	Graphic symbol
1	T1	main terminal 1	mb	
2	T2	main terminal 2		Ν
3	G	gate		
mb	n.c.	mounting base; isolated		sym051
			1 2 3	

# 6. Ordering information

Table 3. Ordering information						
Type number	Package	ckage				
	Name	Description	Version			
BT136X-600E	TO-220F	plastic single-ended package; isolated heatsink mounted; 1 mounting hole; 3-lead TO-220 "full pack"	SOT186A			

# 7. Marking

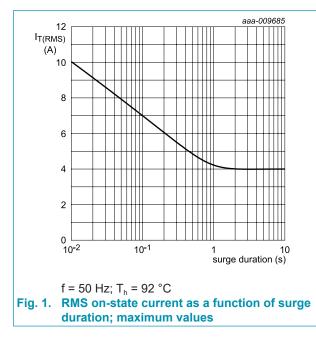
Table 4. Marking codes							
Type number	Marking codes						
BT136X-600E	BT136X-600E						

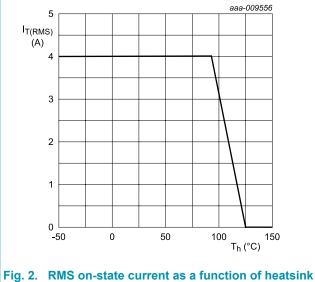
# 8. Limiting values

#### Table 5. Limiting values

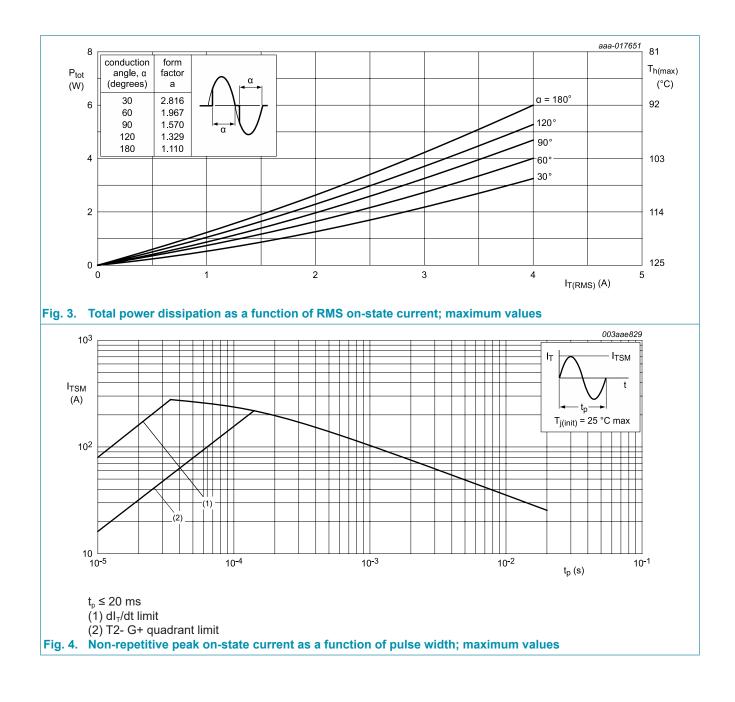
In accordance with the Absolute Maximum Rating System (IEC 60134).

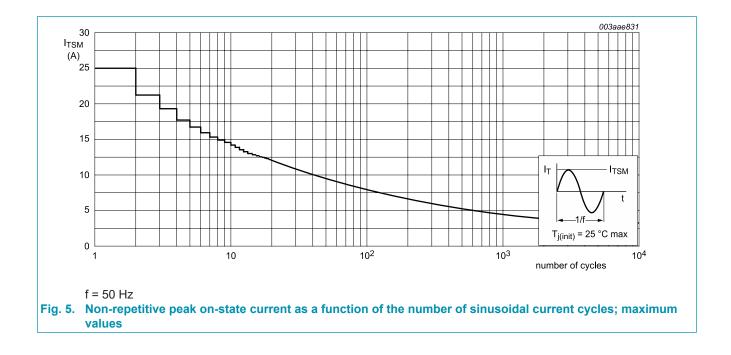
Symbol	Parameter	Conditions	Values	Unit
$V_{\text{DRM}}$	repetitive peak off-state voltage		600	V
I <sub>T(RMS)</sub>	RMS on-state current	full sine wave; T <sub>h</sub> ≤92 °C; <u>Fig 1</u> ; <u>Fig 2</u> ; <u>Fig 3</u>	4	A
I <sub>TSM</sub>	non-repetitive peak on- state current	full sine wave; T <sub>j(init)</sub> = 25 °C; t <sub>p</sub> = 20 ms; Fig 4; Fig 5	25	A
		full sine wave; $T_{j(init)}$ = 25 °C; $t_p$ = 16.7 ms	27	А
l <sup>2</sup> t	I <sup>2</sup> t for fusing	t <sub>P</sub> = 10 ms; SIN	3.1	A <sup>2</sup> s
dl <sub>⊤</sub> /dt	rate of rise of on-state current	I <sub>G</sub> = 20 mA; T2+ G+	50	A/µs
		I <sub>G</sub> = 20 mA; T2+ G-	50	A/µs
		I <sub>G</sub> = 20 mA; T2- G-	50	A/µs
		I <sub>G</sub> = 50 mA; T2- G+	10	A/µs
I <sub>GM</sub>	peak gate current		2	А
P <sub>GM</sub>	peak gate power		5	W
P <sub>G(AV)</sub>	average gate power	over any 20 ms period	0.5	W
T <sub>stg</sub>	storage temperature		-40 to 150	°C
Tj	junction temperature		125	°C





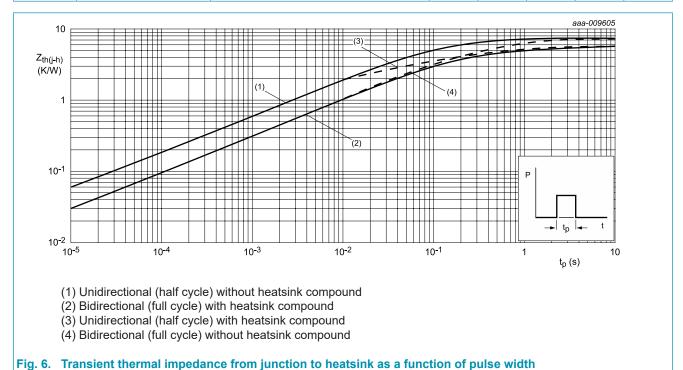
temperature; maximum values





## 9. Thermal characteristics

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
$R_{\text{th(j-h)}}$	thermal resistance from junction to	full or half cycle; with heatsink compound; Fig 6	-	-	5.5	K/W
	heatsink	full or half cycle; without heatsink compound; Fig 6	-	-	7.2	K/W
$R_{\text{th(j-a)}}$	thermal resistance from junction to ambient	in free air	-	55	-	K/W

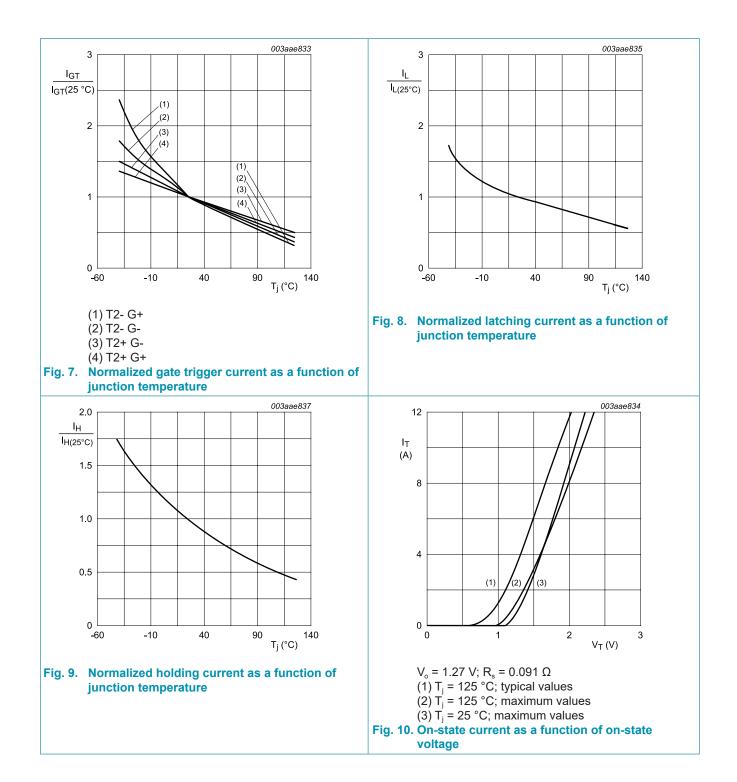


### **10. Isolation characteristics**

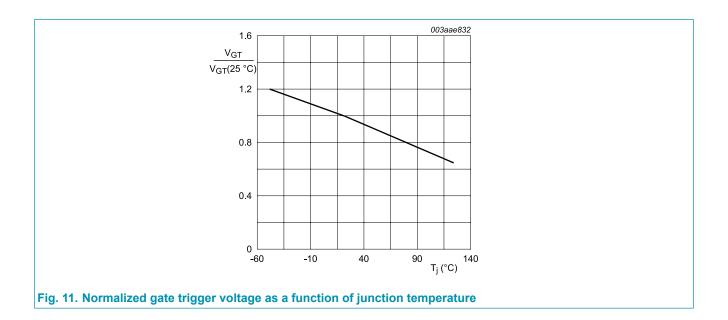
Fable 7. Isolation characteristics								
Symbol	Parameter	Conditions		Min	Тур	Max	Unit	
$V_{isol(RMS)}$	RMS isolation voltage	from all terminals to external heatsink; sinusoidal waveform; clean and dust free; 50 Hz $\leq$ f $\leq$ 60 Hz; RH $\leq$ 65 %; T <sub>h</sub> = 25 °C		-	-	2500	V	
C <sub>isol</sub>	isolation capacitance	from main terminal 2 to external heatsink; f = 1 MHz; $T_h$ = 25 °C		-	10	-	pF	

# **11. Characteristics**

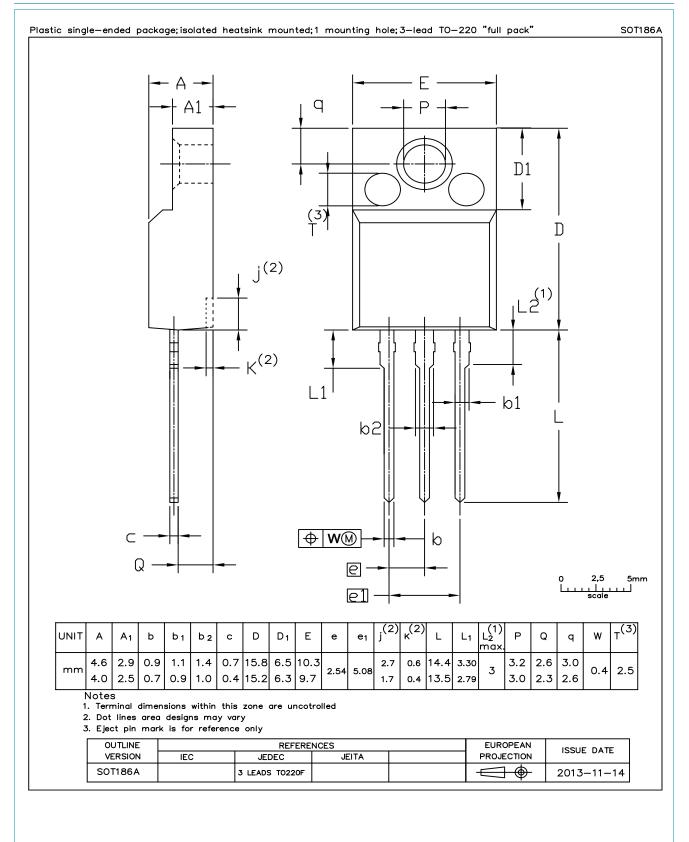
Parameter	Conditions	Min	Тур	Max	Unit
aracteristics		I			_
gate trigger current	$V_{D}$ = 12 V; I <sub>T</sub> = 0.1 A; T2+ G+; T <sub>j</sub> = 25 °C; <u>Fig. 7</u>	-	2.5	10	mA
	$V_{D}$ = 12 V; I <sub>T</sub> = 0.1 A; T2+ G-; T <sub>j</sub> = 25 °C; <u>Fig. 7</u>	-	4	10	mA
	V <sub>D</sub> = 12 V; I <sub>T</sub> = 0.1 A; T2- G-; T <sub>j</sub> = 25 °C; <u>Fig. 7</u>	-	5	10	mA
	$V_{D}$ = 12 V; I <sub>T</sub> = 0.1 A; T2- G+; T <sub>j</sub> = 25 °C; <u>Fig. 7</u>	-	11	25	mA
latching current	$V_{D}$ = 12 V; I <sub>G</sub> = 0.1 A; T2+ G+; T <sub>j</sub> = 25 °C; Fig. 8	-	3	15	mA
	$V_{D}$ = 12 V; I <sub>G</sub> = 0.1 A; T2+ G-; T <sub>j</sub> = 25 °C; Fig. 8	-	10	20	mA
	$V_D = 12 \text{ V}; \text{ I}_G = 0.1 \text{ A}; \text{ T2- G-};$ T <sub>j</sub> = 25 °C; <u>Fig. 8</u>	-	2.5	15	mA
	$V_D = 12 \text{ V}; \text{ I}_G = 0.1 \text{ A}; \text{ T2- G+};$ T <sub>j</sub> = 25 °C; <u>Fig. 8</u>	-	4	20	mA
holding current	V <sub>D</sub> = 12 V; T <sub>j</sub> = 25 °C; <u>Fig. 9</u>	-	2.2	15	mA
on-state voltage	I <sub>T</sub> = 5 A; T <sub>j</sub> = 25 °C; <u>Fig. 10</u>	-	1.4	1.7	V
gate trigger voltage	V <sub>D</sub> = 12 V; I <sub>T</sub> = 0.1 A; T <sub>j</sub> = 25 °C; Fig. 11	-	0.7	1	V
	V <sub>D</sub> = 400 V; I <sub>T</sub> = 0.1 A; T <sub>j</sub> = 125 °C; <u>Fig. 11</u>	0.25	0.4	-	V
off-state current	V <sub>D</sub> = 600 V; T <sub>j</sub> = 125 °C	-	0.1	0.5	mA
characteristics	· · · · · ·	I			
rate of rise of off-state voltage	$V_{DM}$ = 402 V; T <sub>j</sub> = 125 °C; (V <sub>DM</sub> = 67% of V <sub>DRM</sub> ); exponential waveform; gate open circuit	-	50	-	V/µs
gate-controlled turn-on time	$V_{\rm D}$ = 600 V; I <sub>TM</sub> = 6 A; I <sub>G</sub> = 0.1 A; dI <sub>G</sub> /dt = 5 A/µs	-	2	-	μs
	aracteristics      gate trigger current      gate trigger current      latching current      holding current      on-state voltage      gate trigger voltage      off-state current      characteristics      rate of rise of off-state voltage      gate-controlled turn-on	aracteristics      gate trigger current $V_D = 12 \text{ V}; I_T = 0.1 \text{ A}; \text{ T2+ G+}; \\ T_J = 25 ^{\circ}\text{C}; Fig. 7 \\ V_D = 12 \text{ V}; I_T = 0.1 \text{ A}; \text{T2+ G-}; \\ T_J = 25 ^{\circ}\text{C}; Fig. 7 \\ V_D = 12 \text{ V}; I_T = 0.1 \text{ A}; \text{T2- G-}; \\ T_J = 25 ^{\circ}\text{C}; Fig. 7 \\ V_D = 12 \text{ V}; I_T = 0.1 \text{ A}; \text{T2- G+}; \\ T_J = 25 ^{\circ}\text{C}; Fig. 7 \\ V_D = 12 \text{ V}; I_G = 0.1 \text{ A}; \text{T2+ G+}; \\ T_J = 25 ^{\circ}\text{C}; Fig. 8 \\ V_D = 12 \text{ V}; I_G = 0.1 \text{ A}; \text{T2+ G+}; \\ T_J = 25 ^{\circ}\text{C}; Fig. 8 \\ V_D = 12 \text{ V}; I_G = 0.1 \text{ A}; \text{T2+ G-}; \\ T_J = 25 ^{\circ}\text{C}; Fig. 8 \\ V_D = 12 \text{ V}; I_G = 0.1 \text{ A}; \text{T2- G-}; \\ T_J = 25 ^{\circ}\text{C}; Fig. 8 \\ V_D = 12 \text{ V}; I_G = 0.1 \text{ A}; \text{T2- G+}; \\ T_J = 25 ^{\circ}\text{C}; Fig. 8 \\ \hline V_D = 12 \text{ V}; I_G = 0.1 \text{ A}; \text{T2- G+}; \\ T_J = 25 ^{\circ}\text{C}; Fig. 8 \\ \hline V_D = 12 \text{ V}; I_G = 0.1 \text{ A}; \text{T2- G+}; \\ T_J = 25 ^{\circ}\text{C}; Fig. 8 \\ \hline V_D = 12 \text{ V}; I_G = 0.1 \text{ A}; \text{T2- G+}; \\ T_J = 25 ^{\circ}\text{C}; Fig. 10 \\ \hline \text{on-state voltage} \qquad I_T = 5 \text{ A}; T_J = 25 ^{\circ}\text{C}; Fig. 9 \\ \hline \text{on-state voltage} \qquad I_T = 5 \text{ A}; T_J = 25 ^{\circ}\text{C}; Fig. 10 \\ \hline V_D = 400 \text{ V}; I_T = 0.1 \text{ A}; T_J = 125 ^{\circ}\text{C}; \\ Fig. 11 \\ \hline V_D = 400 \text{ V}; I_T = 0.1 \text{ A}; T_J = 125 ^{\circ}\text{C}; \\ Fig. 11 \\ \hline V_D = 400 \text{ V}; I_T = 125 ^{\circ}\text{C}; \\ Fig. 11 \\ \hline \text{off-state current} \qquad V_D = 600 \text{ V}; T_J = 125 ^{\circ}\text{C}; (V_{DM} = 67\% \text{ of } V_{DRM}); \text{ exponential waveform}; \text{ gate open circuit} \\ \hline \text{gate-controlled turn-on} \qquad V_D = 600 \text{ V}; I_T = 6 \text{ A}; I_G = 0.1 \text{ A}; \\ \end{array} $	$ \begin{array}{ c c c c c c c c c c c c c c c c c c c$	$ \begin{array}{ c c c c c c c c c c c c c c c c c c c$	



BT136X-600E



### 12. Package outline



# 13. Legal information

#### Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
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